

AMENDMENTS TO THE SPECIFICATION:

Insert the following new paragraph above line 5 of page 1:

This is a divisional of application Serial No. 09/392,466 filed September 9, 1999, now abandoned.

Paragraph starting at line 7 of page 1 has been amended as follows:

This invention relates to a method of producing ceramic thermistor in the form of chips ("ceramic thermistor chips") for surface mounting. ~~The invention also relates to a method of producing such ceramic thermistor chips.~~

Paragraph starting at line 13 of page 2 has been amended as follows:

It is therefore an object of this invention to provide a method of producing a new kind of ceramic thermistor chip which can be produced at a reduced cost ~~and a method of producing such ceramic thermistor chips.~~

Paragraph starting at line 4 of page 12 has been amended as follows:

~~A ceramic thermistor chip has outer electrodes electrolytically formed on both end parts of a ceramic thermistor element and the portions of the surface of the ceramic thermistor element not covered by these outer electrodes are entirely covered by an organic insulating layer such as an acrylate resin layer or a ceramic layer with specific resistance greater than that of the thermistor element such as a material having as its principal component one or more oxides containing two or more metals selected from Mn, Ni, Co, Fe, Cu and Al and one or more metals selected from Zn, Al, W, Zr, Sb, Y, Sm, Ti and Fe.~~ Ceramic thermistor chips are produced by stacking ceramic green sheets, cutting and baking them to obtain a ceramic thermistor element, forming a high-resistance layer entirely covering its outer surfaces except specified end parts, and thereafter forming electrolytically plated layers on these end parts such that the outer

surfaces are entirely covered by the high-resistance layer except where the electrolytically plated layers are formed.